

ABSTRACT

A semiconductor package in which solder balls can be loaded on an encapsulated resin to reduce the package area and a method for producing the semiconductor package. An apparatus for carrying out the method includes a first insulating substrate 5 carrying a mounting portion 3 for mounting a semiconductor device 2 and a first electrically conductive pattern 4 electrically connected to the semiconductor device 2, a sidewall section 6 formed upright around the mounting portion of the first insulating substrate, a cavity 7 defined by the first insulating substrate 5 and the sidewall section and encapsulated by an encapsulating resin 12 as the semiconductor device 2 is mounted on the mounting portion 3 and a second insulating substrate 10 provided in the cavity 7 and on the sidewall section 6 and carrying a second electrically conductive pattern 31 electrically connected to the first electrically conductive pattern 4 via plated through-holes 26 formed in the sidewall section 6. A solder land 9 is provided in a lattice on one entire surface of the second insulating substrate 10.